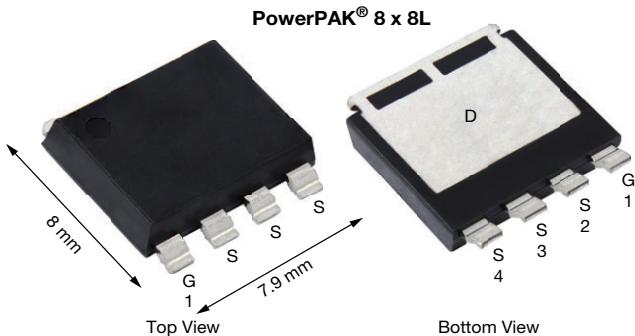


## Automotive N-Channel 40 V (D-S) 175 °C MOSFET

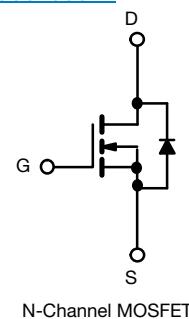


### FEATURES

- TrenchFET® Gen IV power MOSFET
- AEC-Q101 qualified
- 100 %  $R_g$  and UIS tested
- Thin 1.6 mm package
- Very low thermal resistance
- Material categorization:  
for definitions of compliance please see  
[www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
**HALOGEN**  
**FREE**



<b>PRODUCT SUMMARY</b>	
$V_{DS}$ (V)	40
$R_{DS(on)}$ ( $\Omega$ ) at $V_{GS} = 10$ V	0.0019
$I_D$ (A)	233
Configuration	Single
Package	PowerPAK 8 x 8L

<b>ABSOLUTE MAXIMUM RATINGS</b> ( $T_C = 25$ °C, unless otherwise noted)			
PARAMETER	SYMBOL	LIMIT	UNIT
Drain-source voltage	$V_{DS}$	40	
Gate-source voltage	$V_{GS}$	$\pm 20$	V
Continuous drain current	$I_D$	233	
$T_C = 125$ °C		134	
Continuous source current (diode conduction)	$I_S$	170	A
Pulsed drain current <sup>a</sup>	$I_{DM}$	930	
Single pulse avalanche current	$I_{AS}$	38	
Single pulse avalanche energy	$E_{AS}$	72	mJ
Maximum power dissipation	$P_D$	187	
$T_C = 125$ °C		62	W
Operating junction and storage temperature range	$T_J, T_{stg}$	-55 to +175	
Soldering recommendations (peak temperature) <sup>c</sup>		260	°C

<b>THERMAL RESISTANCE RATINGS</b>			
PARAMETER	SYMBOL	LIMIT	UNIT
Junction-to-ambient	$R_{thJA}$	44	
Junction-to-case (drain)	$R_{thJC}$	0.8	°C/W

#### Notes

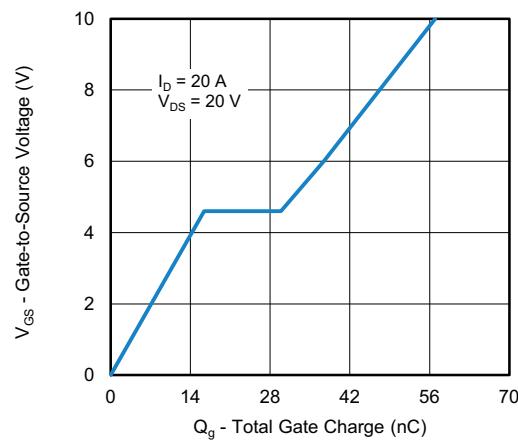
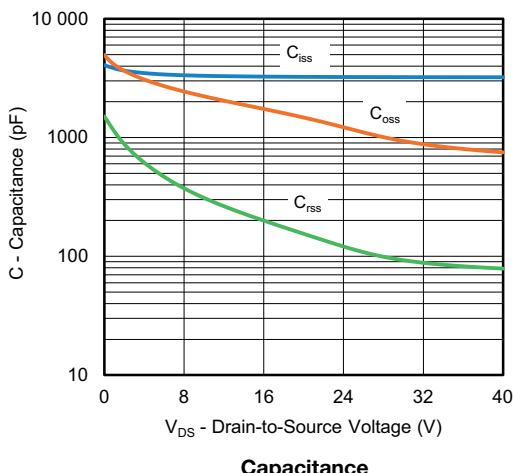
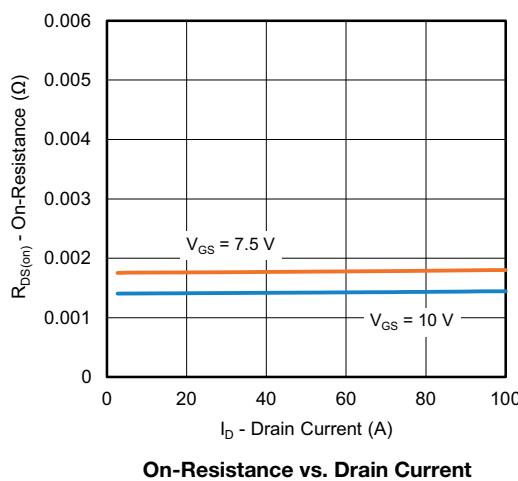
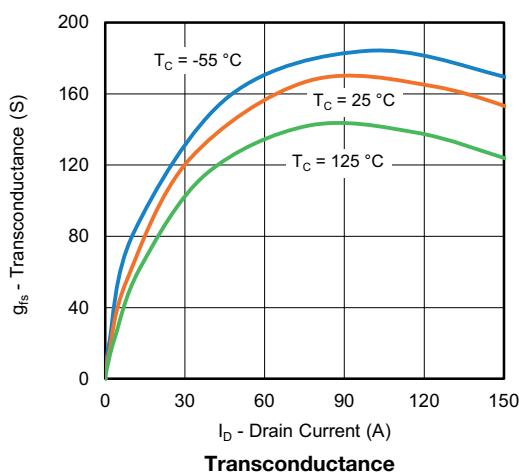
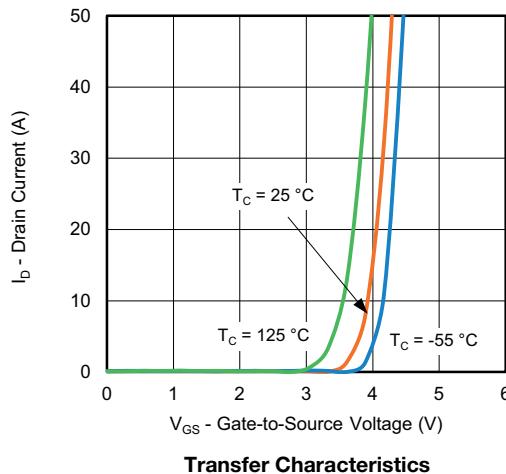
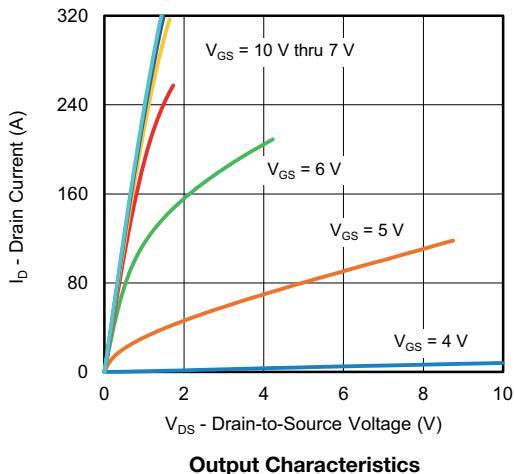
- Pulse test; pulse width  $\leq 300$   $\mu$ s, duty cycle  $\leq 2$  %
- When mounted on 1" square PCB (FR4 material)
- See solder profile ([www.vishay.com/doc?73257](http://www.vishay.com/doc?73257)). The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection

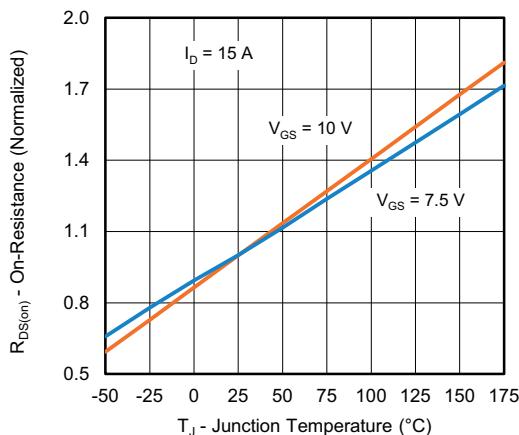
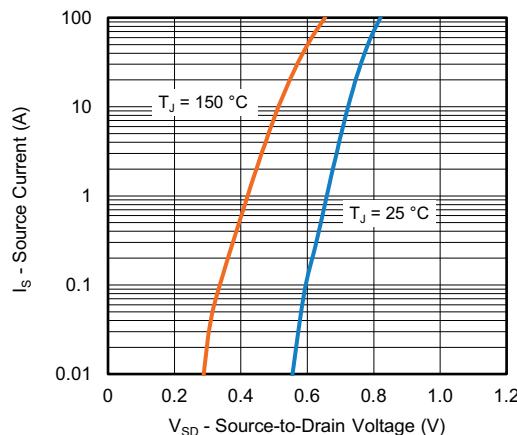
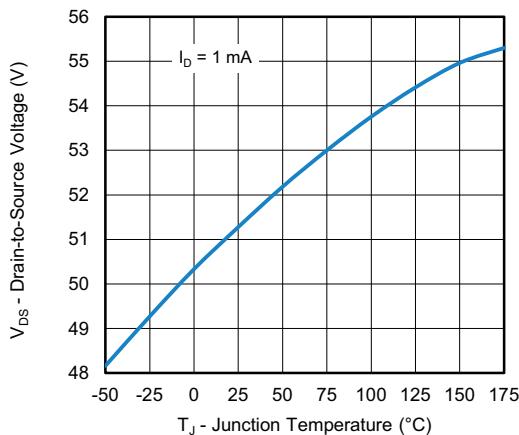
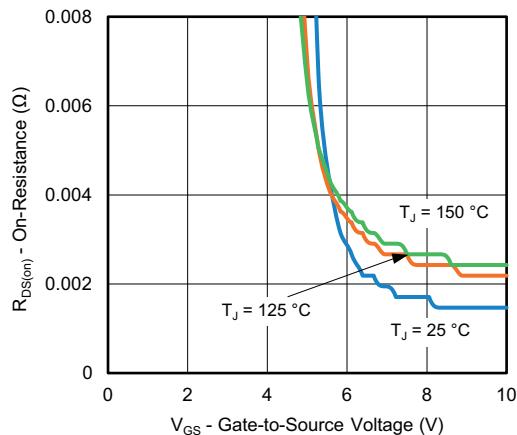
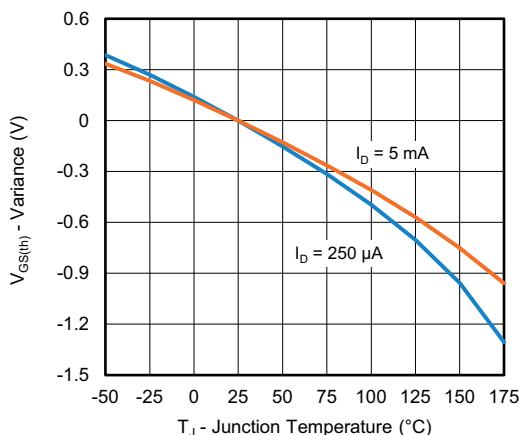
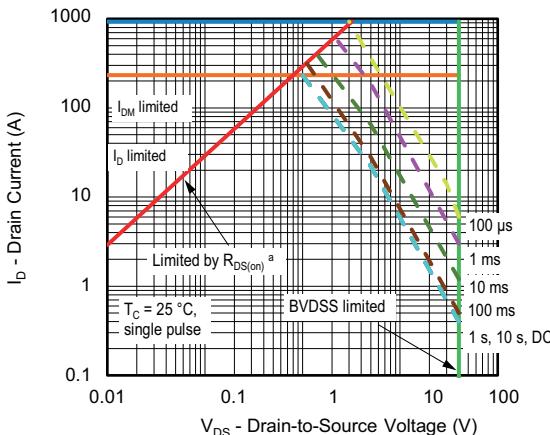
<b>SPECIFICATIONS</b> ( $T_C = 25^\circ\text{C}$ , unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
<b>Static</b>							
Drain-source breakdown voltage	$V_{DS}$	$V_{GS} = 0$ , $I_D = 250 \mu\text{A}$		40	-	-	V
Gate-source threshold voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}$ , $I_D = 250 \mu\text{A}$		2	2.8	3.5	
Gate-source leakage	$I_{GSS}$	$V_{DS} = 0 \text{ V}$ , $V_{GS} = \pm 20 \text{ V}$		-	-	$\pm 100$	nA
Zero gate voltage drain current	$I_{DSS}$	$V_{GS} = 0 \text{ V}$	$V_{DS} = 40 \text{ V}$	-	-	1	$\mu\text{A}$
		$V_{GS} = 0 \text{ V}$	$V_{DS} = 40 \text{ V}$ , $T_J = 125^\circ\text{C}$	-	-	50	
		$V_{GS} = 0 \text{ V}$	$V_{DS} = 40 \text{ V}$ , $T_J = 175^\circ\text{C}$	-	-	150	
On-state drain current <sup>a</sup>	$I_{D(\text{on})}$	$V_{GS} = 10 \text{ V}$	$V_{DS} \geq 5 \text{ V}$	100	-	-	A
Drain-source on-state resistance <sup>a</sup>	$R_{DS(\text{on})}$	$V_{GS} = 10 \text{ V}$	$I_D = 20 \text{ A}$	-	0.0015	0.0019	$\Omega$
		$V_{GS} = 10 \text{ V}$	$I_D = 20 \text{ A}$ , $T_J = 125^\circ\text{C}$	-	-	0.003	
		$V_{GS} = 10 \text{ V}$	$I_D = 20 \text{ A}$ , $T_J = 175^\circ\text{C}$	-	-	0.0035	
Forward transconductance <sup>b</sup>	$g_{fs}$	$V_{DS} = 15 \text{ V}$ , $I_D = 30 \text{ A}$		-	120	-	S
<b>Dynamic</b> <sup>b</sup>							
Input capacitance	$C_{iss}$	$V_{GS} = 0 \text{ V}$	$V_{DS} = 25 \text{ V}$ , $f = 1 \text{ MHz}$	-	3316	4643	$\text{pF}$
Output capacitance	$C_{oss}$			-	1137	1592	
Reverse transfer capacitance	$C_{rss}$			-	134	188	
Total gate charge <sup>c</sup>	$Q_g$	$V_{GS} = 10 \text{ V}$	$V_{DS} = 20 \text{ V}$ , $I_D = 20 \text{ A}$	-	61	92	$\text{nC}$
Gate-source charge <sup>c</sup>	$Q_{gs}$			-	17	-	
Gate-drain charge <sup>c</sup>	$Q_{gd}$			-	17	-	
Gate resistance	$R_g$	$f = 1 \text{ MHz}$		0.8	1.7	2.6	$\Omega$
Turn-on delay time <sup>c</sup>	$t_{d(\text{on})}$	$V_{DD} = 20 \text{ V}$ , $R_L = 1.0 \Omega$ , $I_D \geq 20 \text{ A}$ , $V_{GEN} = 10 \text{ V}$ , $R_g = 1 \Omega$	$V_{DS} = 20 \text{ V}$ , $I_D = 20 \text{ A}$	-	17	27	$\text{ns}$
Rise time <sup>c</sup>	$t_r$			-	19	29	
Turn-off delay time <sup>c</sup>	$t_{d(\text{off})}$			-	30	45	
Fall time <sup>c</sup>	$t_f$			-	10	15	
<b>Source-Drain Diode Ratings and Characteristics</b> <sup>b</sup>							
Reverse recovery time	$t_{rr}$	$V_{DD} = 32 \text{ V}$ , $I_{FM} = 15 \text{ A}$ , $di/dt = 100 \text{ A}/\mu\text{s}$		-	40	80	$\text{ns}$
Reverse recovery charge	$Q_{rr}$			-	34	68	
Reverse recovery current	$I_{RM}$			-	-1.5	-	
Pulsed current <sup>a</sup>	$I_{SM}$			-	-	660	A
Forward voltage	$V_{SD}$	$I_F = 50 \text{ A}$ , $V_{GS} = 0$		-	0.8	1.1	V

**Notes**

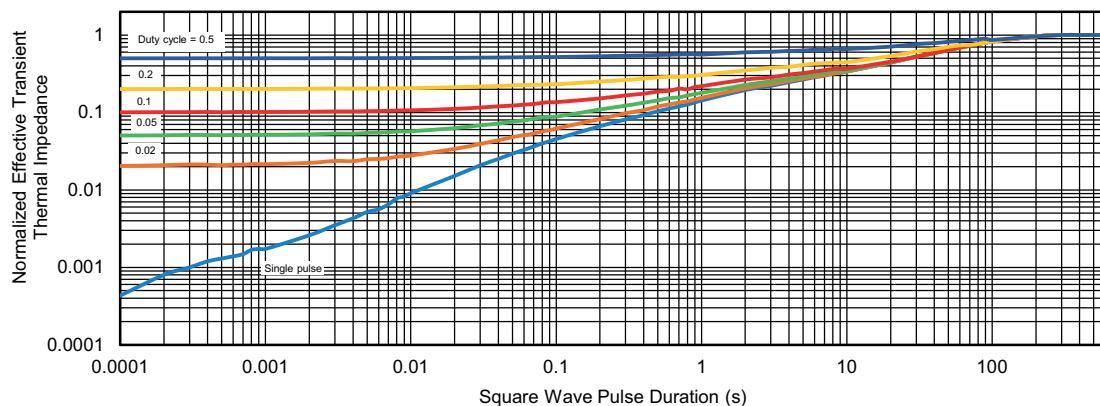
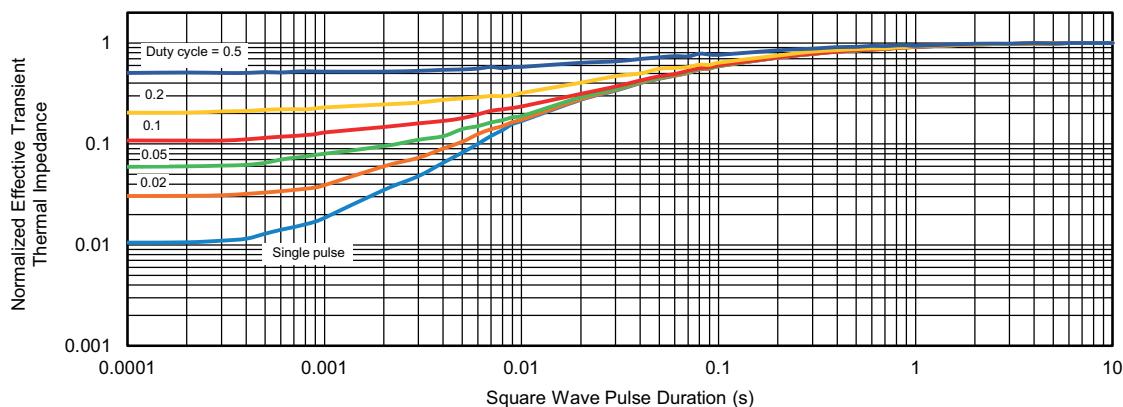
- a. Pulse test; pulse width  $\leq 300 \mu\text{s}$ , duty cycle  $\leq 2\%$
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**TYPICAL CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$ , unless otherwise noted)


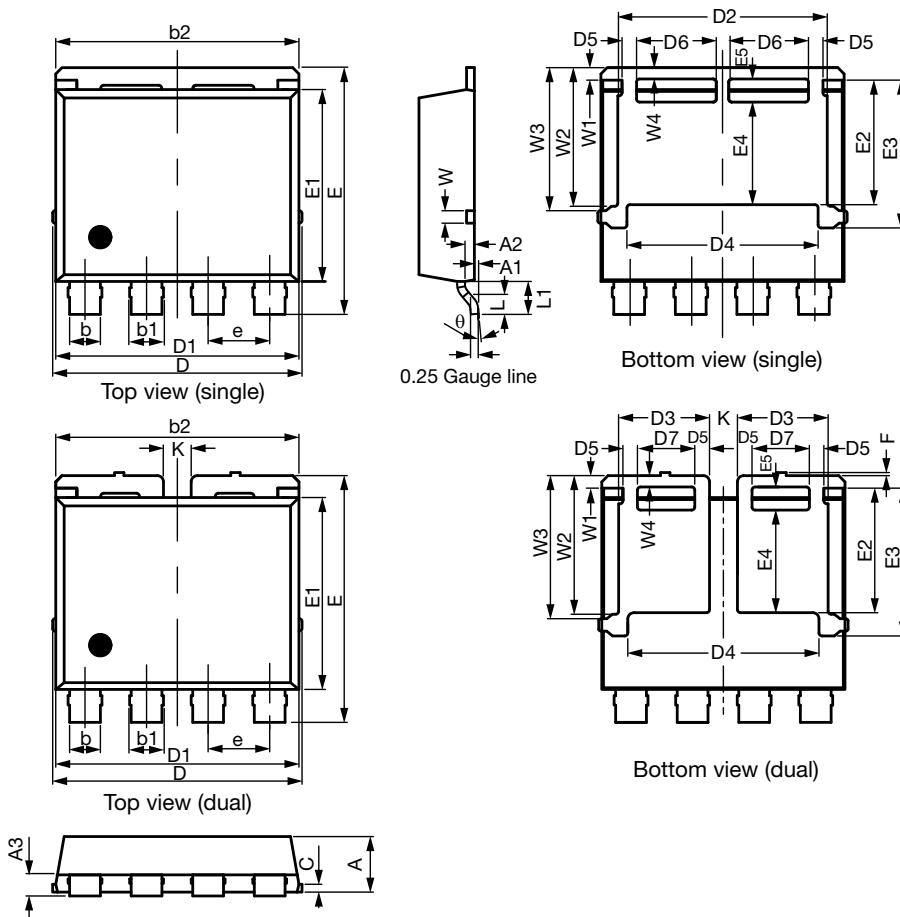
**TYPICAL CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$ , unless otherwise noted)

**On-Resistance vs. Junction Temperature**

**Source Drain Diode Forward Voltage**

**Drain Source Breakdown vs. Junction Temperature**

**On-Resistance vs. Gate-to-Source Voltage**

**Threshold Voltage**

**Safe Operating Area**
**Note**

a.  $V_{GS} >$  minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

**THERMAL RATINGS ( $T_A = 25^\circ\text{C}$ , unless otherwise noted)**

**Normalized Thermal Transient Impedance, Junction-to-Ambient**

**Normalized Thermal Transient Impedance, Junction-to-Case**

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## PowerPAK® 8 x 8L Case Outline



DIM.	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	1.70	1.80	1.90	0.067	0.071	0.075
A1	0.00	0.08	0.13	0.000	0.003	0.005
A2	0.25	0.30	0.35	0.010	0.012	0.014
A3	0.55	0.62	0.70	0.022	0.024	0.028
b	0.92	1.00	1.08	0.036	0.039	0.043
b1	1.02	1.10	1.18	0.040	0.043	0.046
b2	7.80	7.90	8.00	0.307	0.311	0.315
c	0.20	0.25	0.30	0.008	0.010	0.012
D	8.00	8.10	8.25	0.315	0.319	0.325
D1	7.80	7.90	8.00	0.307	0.311	0.315
D2	6.70	6.80	6.90	0.264	0.268	0.272
D3	2.85	2.95	3.05	0.112	0.116	0.120
D4	6.11	6.21	6.31	0.241	0.244	0.248
D5	0.37	0.47	0.57	0.015	0.019	0.022
D6	2.49	2.59	2.69	0.098	0.102	0.106
D7	1.76	1.86	1.96	0.069	0.073	0.077

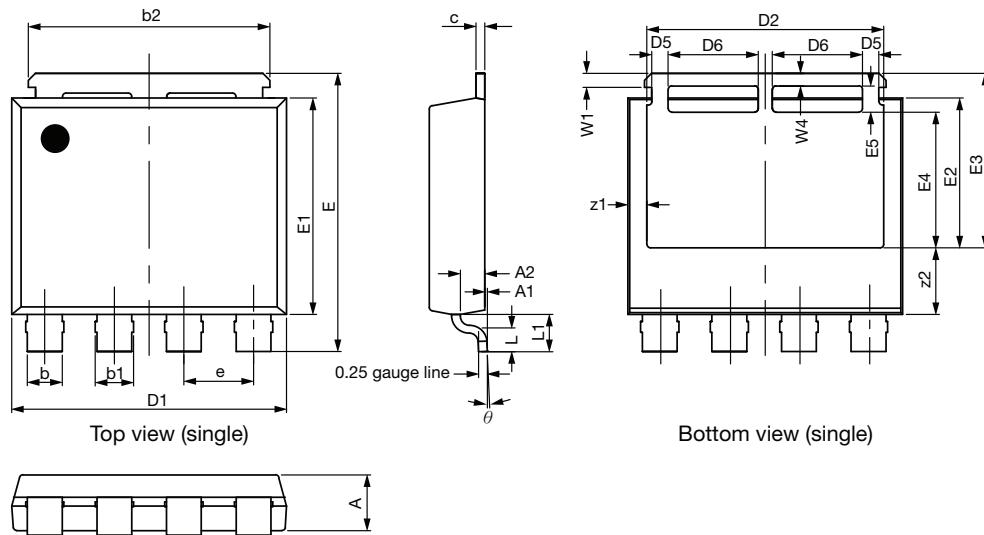


DIM.	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
e	1.95	2.00	2.05	0.077	0.079	0.081
E	7.90	8.00	8.10	0.311	0.315	0.319
E1	6.12	6.22	6.32	0.241	0.245	0.249
E2	3.94	4.04	4.14	0.140	0.159	0.163
E3	4.69	4.79	4.89	0.185	0.189	0.193
E4	3.23	3.33	3.43	0.127	0.131	0.135
E5	0.65	0.75	0.85	0.026	0.030	0.033
F	0.00	0.10	0.15	0.000	0.004	0.006
L	0.62	0.72	0.82	0.024	0.028	0.032
L1	0.92	1.07	1.22	0.036	0.042	0.048
K	0.80	0.90	1.00	0.031	0.035	0.039
W	0.30	0.40	0.50	0.012	0.016	0.020
W1	0.30	0.40	0.50	0.012	0.016	0.020
W2	4.39	4.49	4.59	0.173	0.177	0.181
W3	4.54	4.64	4.74	0.179	0.183	0.187
W4	0.32	0.37	0.42	0.013	0.015	0.017
$\theta$	6°	10°	14°	6°	10°	14°

C17-1388-Rev. B, 16-Oct-17

DWG: 6026

## PowerPAK® 8 x 8L BWL Case Outline 2



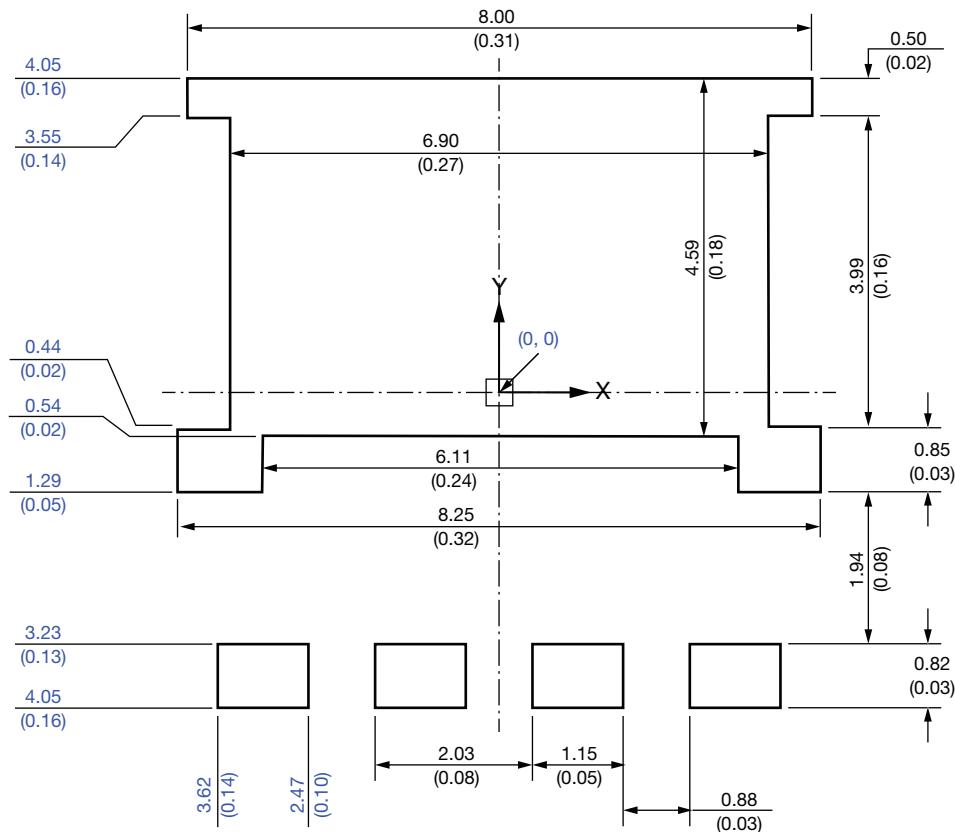
DIM.	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	1.50	1.60	1.70	0.059	0.063	0.067
A1	0.00	-	0.127	0.000	-	0.005
A2	0.655	0.705	0.755	0.026	0.028	0.030
b	0.92	1.00	1.08	0.036	0.039	0.043
b1	1.02	1.10	1.18	0.040	0.043	0.046
b2	6.84	6.94	7.04	0.269	0.273	0.277
c	0.20	0.25	0.30	0.008	0.010	0.012
D1	7.80	7.90	8.00	0.307	0.311	0.315
D2	6.70	6.80	6.90	0.264	0.268	0.272
D5	0.37	0.47	0.57	0.015	0.019	0.022
D6	2.49	2.59	2.69	0.098	0.102	0.106
e	1.97	2.00	2.03	0.078	0.079	0.080
E	7.90	8.00	8.10	0.311	0.315	0.319
E1	6.12	6.22	6.32	0.241	0.245	0.249
E2	4.21	4.31	4.41	0.166	0.170	0.174
E3	4.92	5.02	5.12	0.194	0.198	0.202
E4	3.80	3.90	4.00	0.150	0.154	0.157
E5	0.65	0.75	0.85	0.026	0.030	0.033
L	0.61	0.68	0.75	0.024	0.027	0.030
L1	1.00	1.07	1.15	0.039	0.042	0.045
W1	0.30	0.40	0.50	0.012	0.016	0.020
W4	0.32	0.37	0.42	0.013	0.015	0.017
z1	0.45	0.55	0.65	0.018	0.022	0.026
z2	1.81	1.91	2.01	0.071	0.075	0.079
$\theta$	0°	-	5°	0°	-	5°

ECN: S19-0643-Rev. B, 05-Aug-2019  
DWG: 6073

**Note**

- Millimeter will govern

## Recommended Minimum PADs for PowerPAK® 8 x 8L Single


**Note**

- Linear dimensions are in black, the same information is provided in ordinate dimensions which are in blue.



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